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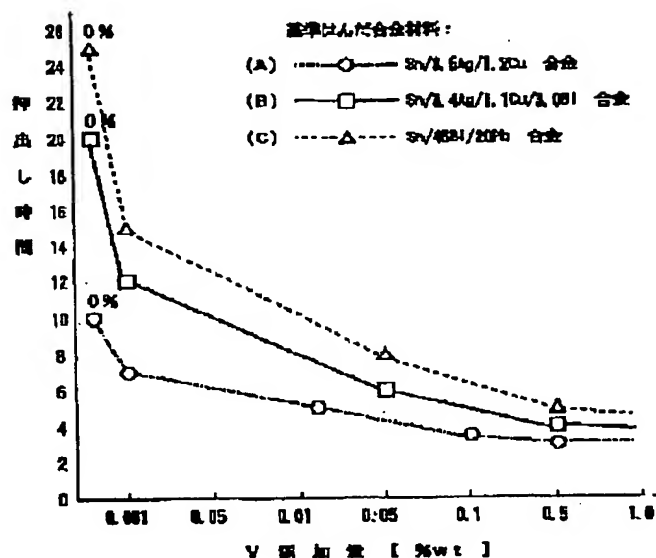
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APPLICANT : NIPPON HANDA KK;

INVENTOR : MURATA TORU;

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TITLE : IMPROVED WORKABILITY SOLDER



ABSTRACT : PROBLEM TO BE SOLVED: To eliminate the defect resulting from that a solder containing bismuth, etc., is hard and brittle as compared to a tin/lead alloy solder resulting in poor plastic workability, poor extrusion workability and partly not extrusion workable.

SOLUTION: In an improved workability solder produced such that 0.001-0.5 wt.% vanadium is added into the solder containing tin, by adding vanadium, the plastic workability is improved, concurrently the toughness of the alloy is improved. For example, an improved workability solder contains 96-90 wt.% Sn, 3.0-3.5 wt.% Ag, 0.7-1.2 wt.% Cu,  $\leq 3$  wt.% Bi, 0.001-0.5 wt.% V.

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